

<b>Electronic Patent Application Fee Transmittal</b>				
<b>Application Number:</b>	10565587			
<b>Filing Date:</b>	22-Feb-2007			
<b>Title of Invention:</b>	Copper Foil with Ultra Thin Adhesive Layer, and a Method for Manufacturing the Copper Foil with Ultra Thin Adhesive Layer			
<b>First Named Inventor/Applicant Name:</b>	Tetsuro Sato			
<b>Filer:</b>	Sean Christophe Myers-Payne/Sonja Combest			
<b>Attorney Docket Number:</b>	3209-111			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>810</b>